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Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea5k2f35c2l

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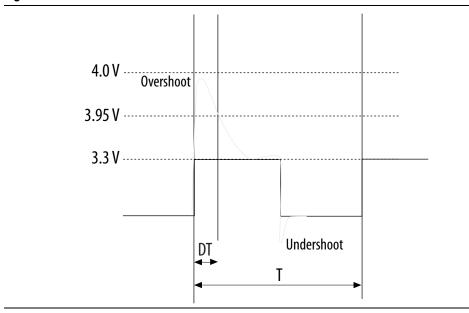
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Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Table 5. Maximum Allowed Overshoot During Transitions

Symbol	Description	Condition (V)	Overshoot Duration as % @ T _J = 100°C	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
Vi (AC)	AC input voltage	4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Figure 1. Stratix V Device Overshoot Duration



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Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC} Core voltage and periphery circuitry pov supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾		_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
1,	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
V_{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V _I	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	_	0	_	V _{CCIO}	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T _J	Operating junction temperature	Industrial	-40	_	100	°C

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Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
t _{RAMP} Power supply ramp time	Power cupply ramp time	Standard POR	200 μs	_	100 ms	_
	Power supply ramp time	Fast POR	200 μs	_	4 ms	_

Notes to Table 6:

- (1) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V
(1), (3)	side)	७४, ७७, ७१	2.375	2.5	2.625	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V
$(1), (\overline{3})$	side)	রম, রহ	2.375	2.5	2.625	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V_{CCHIP_R}	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
$V_{\text{CCHSSI_R}}$	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
			0.82	0.85	0.88	- V
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	
(2)	Treceiver arialog power supply (left side)		0.97	1.0	1.03	
			1.03	1.05	1.07	

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Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit	
		3.0	0.189		
	OCT variation with temperature without recalibration	2.5	0.208		
dR/dT		1.8	0.266	%/°C	
		1.5	0.273		
		1.2	0.317		

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to $85^\circ\text{C}.$

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

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You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 6 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed e 1	Trar	sceive Grade	r Speed 2	Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	ı	ı	500	_	ı	500	_	_	500	ps
CMU PLL											
Supported Data Range	_	600	_	12500	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs
t _{pll_lock} (16)	_	_	_	10	_	_	10	_	_	10	μs
ATX PLL											
	VCO post-divider L=2	8000	_	14100	8000	_	12500	8000	_	8500/ 10312.5 (24)	Mbps
Currented Date	L=4	4000	_	7050	4000	_	6600	4000		6600	Mbps
Supported Data Rate Range	L=8	2000	_	3525	2000	_	3300	2000	_	3300	Mbps
Ç	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	1000	_	1762.5	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs
t _{pll_lock} (16)	_			10	_		10	_		10	μs
fPLL											
Supported Data Range	_	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_		μs

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_	_	_	10	_	_	10	_	_	10	μs

Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{I TD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll\ powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{nll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{REF} is 2000 Ω ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) $^{(1)}$

Symbol/	Conditions	5	Transceive Speed Grade	ransceiver eed Grade 2		Transceive peed Grade		Unit		
Description		Min	Тур	Max	Min	Тур	Max	5		
Reference Clock	l		<u>I</u>	U.			<u>I</u>	<u>I</u>		
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	1L, 1.4-V PC	ML, 1.5-V P(CML, 2.5-V I and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS		
otandardo	RX reference clock pin		1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS							
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz		
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz		
Rise time	20% to 80%	_	_	400	_	_	400			
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps		
Duty cycle	_	45	_	55	45	_	55	%		
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz		
Spread-spectrum downspread	PCle		0 to -0.5	_	_	0 to -0.5	_	%		
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω		
Absolute V _{MAX} (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V		
	RX reference clock pin	_	_	1.2	_	_	1.2			
Absolute V _{MIN}	_	-0.4	_	_	-0.4		_	V		
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV		
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000	2)	1	050/1000	2)	mV		
	RX reference clock pin	1	.0/0.9/0.85	(22)	1.0/0.9/0.85 (22)			V		
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV		

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	1
	100 Hz	_	_	-70	_	_	-70	
Transmitter REFCLK	1 kHz	_	_	-90		_	-90	
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz	_	_	-110	_	_	-110	
	≥1 MHz		_	-120	_		-120	1
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)
RREF (17)	_	_	1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency		100	_	125	100		125	MHz
Receiver								
Supported I/O Standards	_		1.4-V PCML	, 1.5-V PCML	_, 2.5-V PCI	ML, LVPEC	L, and LVDS	6
Data rate (Standard PCS) (21)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) (21)	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4	_	_	V
Maximum peak-to-peak	GT channels		_	1.6	_		1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration ⁽¹⁶⁾ , ⁽²⁰⁾	$V_{CCR_GTB} = 1.05 \text{ V} $ $(V_{ICM} = 0.65 \text{ V})$	_	_	2.2	_	_	2.2	V
oomiguration ', ' /	GX channels				(8)		•	•
Minimum differential	GT channels	200	_	_	200		_	mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range (-40° to 100° C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 ⁽¹⁾	MHz
INPFD	Input frequency to the PFD	5	_	325	MHz
FINPFD	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f _{vco} ⁽⁹⁾	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	_	1300	MHz
EINDUTY	Input clock or external feedback clock input duty cycle	40	_	60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	_	_	717 (2)	MHz
Гоит	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 ⁽²⁾	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f _{OUT_EXT}	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 (2)	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 ⁽²⁾	MHz
t _{оитриту}	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
FCOMP	External feedback clock compensation time	_		10	ns
DYCONFIGCLK	Dynamic Configuration Clock used for mgmt_clk and scanclk	_	_	100	MHz
Lock	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
DLOCK	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3		MHz
: CLBW	PLL closed-loop medium bandwidth		1.5		MHz
	PLL closed-loop high bandwidth (7)	_	4	_	MHz
PLL_PSERR	Accuracy of PLL phase shift		_	±50	ps
ARESET	Minimum pulse width on the areset signal	10	_	_	ns

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Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
→ (3) (4)	Input clock cycle-to-cycle jitter (f _{REF} ≥ 100 MHz)	_	_	0.15	UI (p-p)
t _{INCCJ} (3), (4)	Input clock cycle-to-cycle jitter (f _{REF} < 100 MHz)	-750		+750	ps (p-p)
+ (5)	Period Jitter for dedicated clock output ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	175 ⁽¹⁾	ps (p-p)
t _{OUTPJ_DC} (5)	Period Jitter for dedicated clock output (f _{OUT} < 100 MHz)	_	_	17.5 ⁽¹⁾	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
t _{FOUTPJ_DC} (5)	Period Jitter for dedicated clock output in fractional PLL (f _{OUT} < 100 MHz)	_	_	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
+ (5)	Cycle-to-Cycle Jitter for a dedicated clock output $(f_{OUT} \ge 100 \text{ MHz})$	_	_	175	ps (p-p)
t _{outccj_dc} (5)	Cycle-to-Cycle Jitter for a dedicated clock output (f _{OUT} < 100 MHz)	_	_	17.5	mUI (p-p)
+ (5)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
t _{FOUTCCJ_DC} ⁽⁵⁾	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f _{OUT} < 100 MHz)+	_	_	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
t _{OUTPJ_IO} (5),	Period Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	600	ps (p-p)
(8)	Period Jitter for a clock output on a regular I/O (f _{OUT} < 100 MHz)	_	_	60	mUI (p-p)
t _{FOUTPJ 10} (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL (f_{OUT} < 100 MHz)	_	_	60 (10)	mUI (p-p)
t _{outccj_10} (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} \ge 100$ MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} < 100 MHz)	_	_	60 (10)	mUI (p-p)
t _{FOUTCCJ_IO}	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \ge 100$ MHz)	_	_	600 (10)	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL (f_{OUT} < 100 MHz)	_	_	60	mUI (p-p)
t _{CASC_OUTPJ_DC}	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f _{OUT} < 100 MHz)	_	_	17.5	mUI (p-p)
f _{DRIFT}	Frequency drift after PFDENA is disabled for a duration of 100 μs	_	_	±10	%
dK _{BIT}	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k _{VALUE}	Numerator of Fraction	128	8388608	2147483648	_

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 2 of 2)

		Resour	ces Used			Pe	erforman	ce			
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Notes to Table 33:

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Tei	mperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40°	°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	_	200	μΑ
V _{bias,} voltage across diode	0.3	_	0.9	V
Series resistance	_	_	<1	Ω
Diode ideality factor	1.006	1.008	1.010	_

⁽¹⁾ To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

⁽²⁾ When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

⁽³⁾ The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY	C4,I4			IIi.
Symbol		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential	SERDES factor J ≥ 4 LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
I/O Standards - f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t _{x Jitter} - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

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Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 2 of 2)

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

Notes to Table 40:

- (1) The typical value equals the average of the minimum and maximum values.
- (2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Stratix V Devices (1)

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

Notes to Table 41:

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 1 of 2) (2), (3)

Clock Network	Parameter	Symbol	C 1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
NEIWUIK			Min	Max	Min	Max	Min	Max	Min	Max	
Regional	Clock period jitter	t _{JIT(per)}	-50	50	-50	50	-55	55	-55	55	ps
	Cycle-to-cycle period jitter	t _{JIT(cc)}	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t _{JIT(per)}	-75	75	- 75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	t _{JIT(cc)}	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	t _{JIT(duty)}	- 75	75	- 75	75	-90	90	-90	90	ps

⁽¹⁾ This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a −2 speed grade is ±78 ps or ±39 ps.

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Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Member Code		Active Serial (1)	1	Fast Passive Parallel (2)				
Variant		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)		
	D3	4	100	0.344	32	100	0.043		
	D4	4	100	0.534	32	100	0.067		
GS		4	100	0.344	32	100	0.043		
us	D5	4	100	0.534	32	100	0.067		
	D6	4	100	0.741	32	100	0.093		
	D8	4	100	0.741	32	100	0.093		
E	E9	4	100	0.857	32	100	0.107		
_	EB	4	100	0.857	32	100	0.107		

Notes to Table 48:

Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio	
	Disabled	Disabled	1	
FPP ×8	Disabled	Enabled	1	
IFF X0	Enabled	Disabled	2	
	Enabled	Enabled	2	
	Disabled	Disabled	1	
FPP ×16	Disabled	Enabled	2	
IFF XIO	Enabled	Disabled	4	
	Enabled	Enabled	4	

⁽¹⁾ DCLK frequency of 100 MHz using external CLKUSR.

⁽²⁾ Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

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Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + (8576 \times \\ \text{CLKUSR period}) \end{array}$	_	_

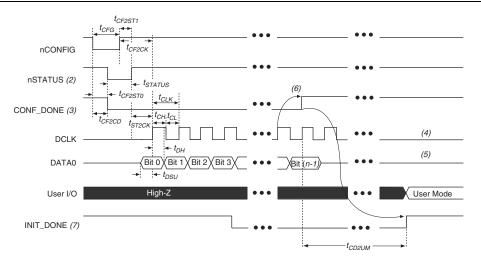
Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions
	SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown: Bit Time 0.5 x TCCS RSKM Sampling Window (SW) 0.5 x TCCS
S	Single-ended voltage referenced I/O standard	The JEDEC standard for SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing: Single-Ended Voltage Referenced I/O Standard Voh Vih(DC) Voh Vih(DC) Voh Vih(DC) Voh Vik(AC) Voh Vik(AC)
	t _C	High-speed receiver and transmitter input and output clock period.
	TCCS (channel- to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{\rm CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under SW in this table).
	t _{DUTY}	High-speed I/O block—Duty cycle on the high-speed transmitter output clock.
T		Timing Unit Interval (TUI) The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_c/w)$
	t _{FALL}	Signal high-to-low transition time (80-20%)
	t _{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
	t _{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
	t _{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
	t _{RISE}	Signal low-to-high transition time (20-80%)
U	_	_

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Document Revision History

Table 61 lists the revision history for this chapter.

Table 61. Document Revision History (Part 1 of 3)

Date	Version	Changes
June 2018	3.9	■ Added the "Stratix V Device Overshoot Duration" figure.
		■ Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.
		■ Changed the minimum value for t _{CD2UMC} in the "PS Timing Parameters for Stratix V Devices" table.
		■ Changed the condition for 100-Ω R _D in the "OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices" table.
April 2017	3.8	■ Changed the minimum value for t _{CD2UMC} in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table
		■ Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table.
		■ Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table.
		■ Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency" table.
June 2016	3.7	■ Added the V _{ID} minimum specification for LVPECL in the "Differential I/O Standard Specifications for Stratix V Devices" table
Julie 2010	3.7	■ Added the I _{OUT} specification to the "Absolute Maximum Ratings for Stratix V Devices" table.
December 2015	3.6	■ Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.
December 2015	3.5	■ Changed the transmitter, receiver, and ATX PLL data rate specifications in the "Transceiver Specifications for Stratix V GX and GS Devices" table.
December 2013	3.3	■ Changed the configuration .rbf sizes in the "Uncompressed .rbf Sizes for Stratix V Devices" table.
		■ Changed the data rate specification for transceiver speed grade 3 in the following tables:
		"Transceiver Specifications for Stratix V GX and GS Devices"
		■ "Stratix V Standard PCS Approximate Maximum Date Rate"
		■ "Stratix V 10G PCS Approximate Maximum Data Rate"
July 2015	3.4	■ Changed the conditions for reference clock rise and fall time, and added a note to the "Transceiver Specifications for Stratix V GX and GS Devices" table.
-		■ Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Transceiver Specifications for Stratix V GX and GS Devices" table.
		■ Changed the t _{CO} maximum value in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table.
		■ Removed the CDR ppm tolerance specification from the "Transceiver Specifications for Stratix V GX and GS Devices" table.

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Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes
		■ Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.
		■ Added the I3YY speed grade to the V _{CC} description in Table 6.
		■ Added the I3YY speed grade to V _{CCHIP_L} , V _{CCHIP_R} , V _{CCHSSI_L} , and V _{CCHSSI_R} descriptions in Table 7.
		■ Added 240-Ω to Table 11.
		■ Changed CDR PPM tolerance in Table 23.
		■ Added additional max data rate for fPLL in Table 23.
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.
		■ Changed CDR PPM tolerance in Table 28.
		■ Added additional max data rate for fPLL in Table 28.
		■ Changed the mode descriptions for MLAB and M20K in Table 33.
		■ Changed the Max value of f _{HSCLK_OUT} for the C2, C2L, I2, I2L speed grades in Table 36.
November 2014	3.3	■ Changed the frequency ranges for C1 and C2 in Table 39.
		■ Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.
		■ Added note about nSTATUS to Table 50, Table 51, Table 54.
		■ Changed the available settings in Table 58.
		■ Changed the note in "Periphery Performance".
		■ Updated the "I/O Standard Specifications" section.
		■ Updated the "Raw Binary File Size" section.
		■ Updated the receiver voltage input range in Table 22.
		■ Updated the max frequency for the LVDS clock network in Table 36.
		■ Updated the DCLK note to Figure 11.
		■ Updated Table 23 VO _{CM} (DC Coupled) condition.
		■ Updated Table 6 and Table 7.
		■ Added the DCLK specification to Table 55.
		■ Updated the notes for Table 47.
		■ Updated the list of parameters for Table 56.
November 2013	3.2	■ Updated Table 28
November 2013	3.1	■ Updated Table 33
November 2013	3.0	■ Updated Table 23 and Table 28
October 2013	2.9	■ Updated the "Transceiver Characterization" section
	2.8	■ Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59
October 2013		■ Added Figure 1 and Figure 3
		■ Added the "Transceiver Characterization" section
		■ Removed all "Preliminary" designations.